

Day 1 - Sep. 14, 2026

Sep. 14, 2026	
13:00	Registration <i>Distribution of Badges</i>
Sep. 14, 2026	
13:45	Opening Remarks ITWS 2026
(15min)	<i>Organisational Items</i> Speaker: Torsten Liese
Session Group A – To Be Clean (Host: Diana Damian)	
Sep. 14, 2026	
14:00	1st Session: Gel-Pak, a DELPHON Industries Company, USA
(30min)	<i>Efficiency Gains In Advanced Wafer-Level-Test: Cleaning Innovations And Solutions</i> Speaker: Jerry Broz
Sep. 14, 2026	
14:30	2nd Session: ACM ENTEGRIS, USA
(30min)	<i>The Dual-Action MEMS Solution: Cleaning Innovation Meets Cost Reduction</i> Speaker: Kenneth Boblak
Sep. 14, 2026	
15:00	3rd Session: BOSCH, Germany
(30min)	<i>Beyond ISO Classes: Cleanroom Control for Wafer Test</i> Speaker: Harald Berger
Session Group B – Inspections (Host: Oliver Nagler)	
Sep. 14, 2026	
15:30	4th Session: SEMICS, Europe
(30min)	<i>F-PMI (Flying PMI): High-Speed Scanning Probe Mark Inspection</i> Speaker: Andrea Vergani
16:00 ~ 17:00 Coffee Break & Poster Sessions	

Sep. 14, 2026	
17:00	5th Session: EVT, Germany
(30min)	<i>Chip Inspection with AI: advanced inspection made easy</i>
	Speaker: Hendrik Schumann
Sep. 14, 2026	
17:30	6th Session: cyberTechnologies, Germany
(30min)	<i>Probe Card Metrology & Rework</i>
	Speaker: Bastian Lindl
19:00	Dinner

Day 2 - Sep. 15, 2026

Session Group C – Test Cost Reductions / Automation (Host: Rainer Holmer)	
Sep. 15, 2026	
09:30	7th Session: HTV ALTER TECHNOLOGY, Germany
(30min)	<i>Last Call or Last Time Buy: Strategies f. Managing Discontinued Semiconductor Processes</i>
	Speaker: Holger Krumme
Sep. 15, 2026	
10:00	8th Session: VX Instruments, Germany
(30min)	<i>Optimizing Test Speed to Reduce Test Costs for SiC/GaN Power Devices</i>
	Speaker: Alexander Loibl
10:30 ~ 11:15	Coffee Break & Poster Sessions
Sep. 15, 2026	
11:15	9th Session: CELADON, USA
(30min)	<i>The Indexer: Automating Probe Card Changes</i>
	Speaker: Paula Mariano

Session Group D – Micro-Thermography / Optical Test (Host: Harald Berger)		
Sep. 15, 2026		
11:45	10th Session: T.I.P.S. & Montanuniversität Leoben, Austria	
(30min)	<i>High Speed Infrared Microscopy for Semiconductor Wafer Probe Heads</i>	
	Speaker: Rainer Gaggl	
Sep. 15, 2026		
12:15	11th Session: PENTAMASTER, Malaysia	
(30min)	<i>Limitations of Wafer Probing for Edge-Coupled PIC...and a Post-Singulation Alternative</i>	
	Speaker: Ari Kuukala	
Sep. 15, 2026		
12:45	12th Session: TECHNOPROBE, Italy	
(30min)	<i>Experimental Evaluation of Optical Coupling Stability using an Eclipse Photonic Probe Card</i>	
	Speaker: Alessia Galli	
Sep. 15, 2026		
13:15	Presentation Awards / Summary of ITWS 2026	
(30min)		
	Speaker: Torsten Liese	
13:45	End of Workshop	

Poster Sessions - see next page →

Poster Sessions (Day 1 & 2)

T.I.P.S., Austria

New approaches to protect probe cards during high-power short-circuit test

Presented by Georg Franz

GlobalFoundries + HTT, Germany

Probing Challenges for High Temperature Testing of MRAM Device

Presented by Alexander Wittig + Mike Strech

CELADON, USA

Revolutionary Solutions for Cryogenic On-Wafer Test

Presented by Garrett Tranquillo

JENOPTIK, Germany

UFO Probe™ Card – Novel Results on All Optical Wafer Level Testing

Presented by Christian Karras